

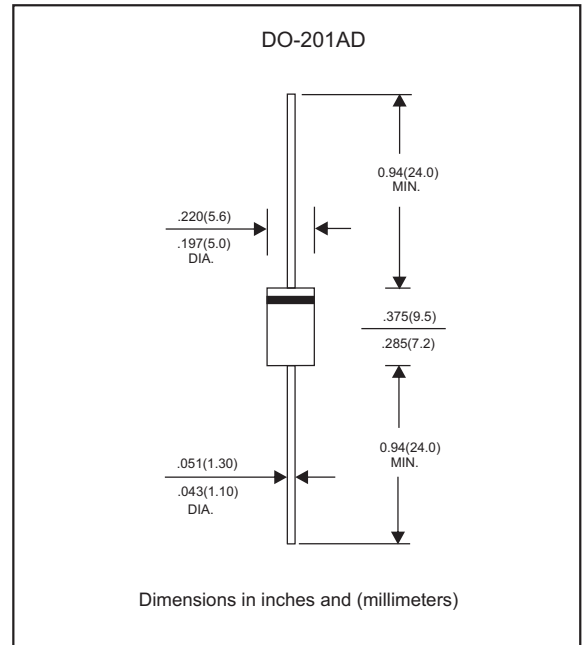
Features

- Axial lead type devices for through hole design
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-201AD/DO-27
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

	SYMBOLS	1N5823	1N5824	1N5825	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC blocking voltage	V_{DC}	20	30	40	V
Maximum average forward rectified current 0.375" (9.5mm) lead length(see fig.1)	I_{AV}	5.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	150.0			A
Maximum instantaneous forward voltage at 5.0A	V_F	0.55			V
Maximum DC reverse current $T_A=25^{\circ}\text{C}$ at rated DC blocking voltage $T_A=100^{\circ}\text{C}$	I_R	0.5			mA
		20.0			
Typical junction capacitance (NOTE 1)	C_J	380			pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	25.0			$^{\circ}\text{C}/\text{W}$
Operating junction temperature range	T_J	-55 to +150			$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150			$^{\circ}\text{C}$

Note:1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, P.C.B. mounted

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

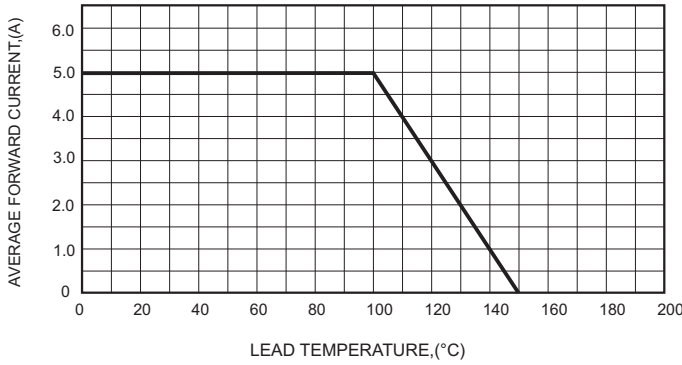


FIG.2-TYPICAL FORWARD CHARACTERISTICS

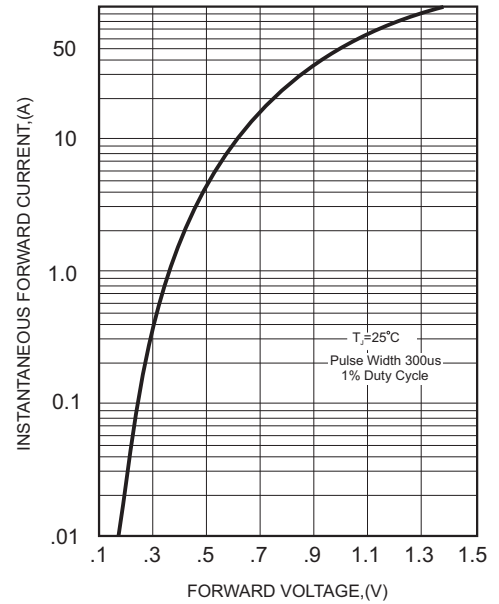


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

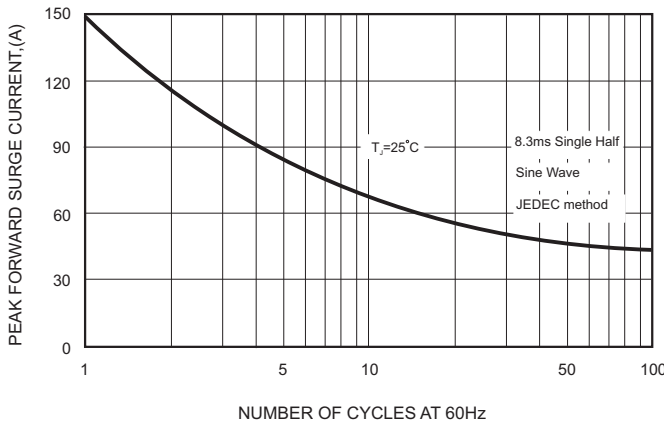


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

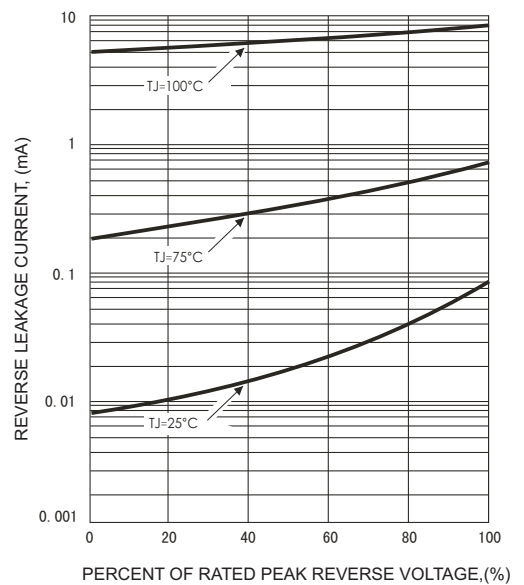
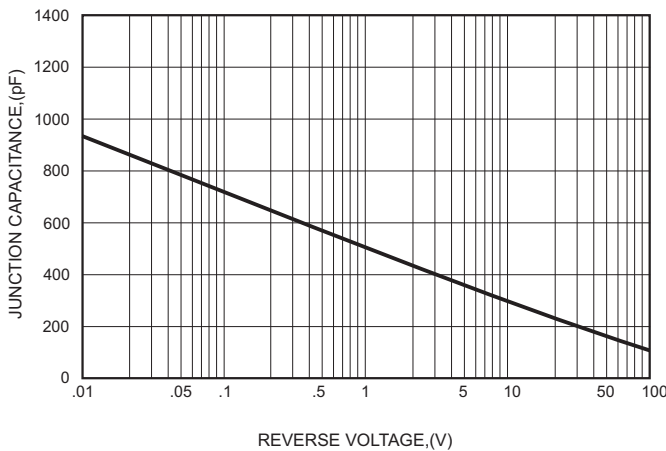




FIG.4-TYPICAL JUNCTION CAPACITANCE



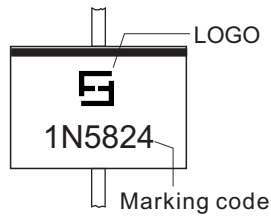
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
1N5823	1N5823
1N5824	1N5824
1N5825	1N5825

Example



Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering

